Plastic Packages for Integrated Circuits

Package Outline Drawing
W11x11.121

121 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.5mm Pitch)
Rev 2, 9/13

NOTES:
1. All dimensions are in millimeters.
3. NSMD refers to non-solder mask defined pad design per Intersil Techbrief TB451